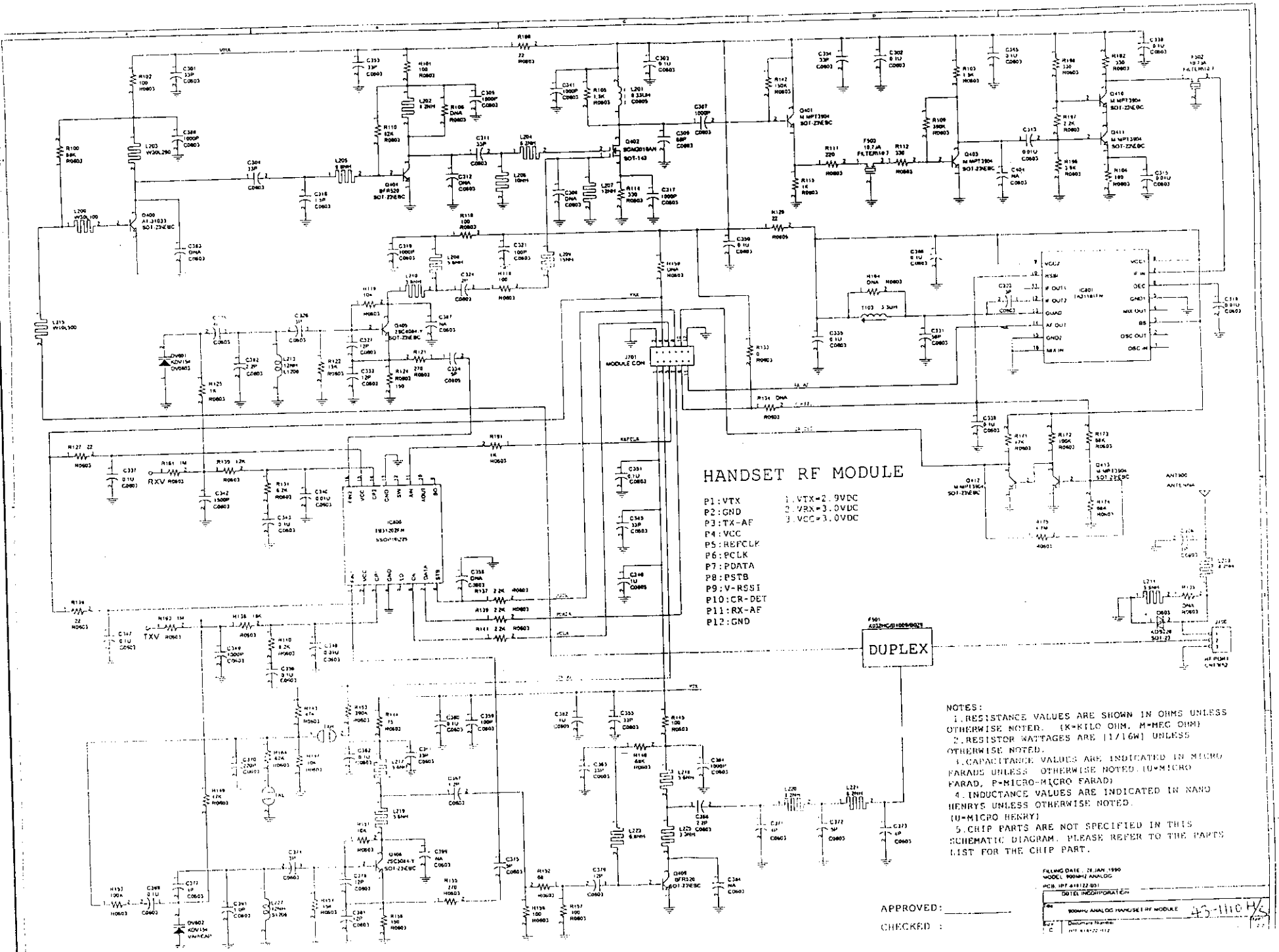
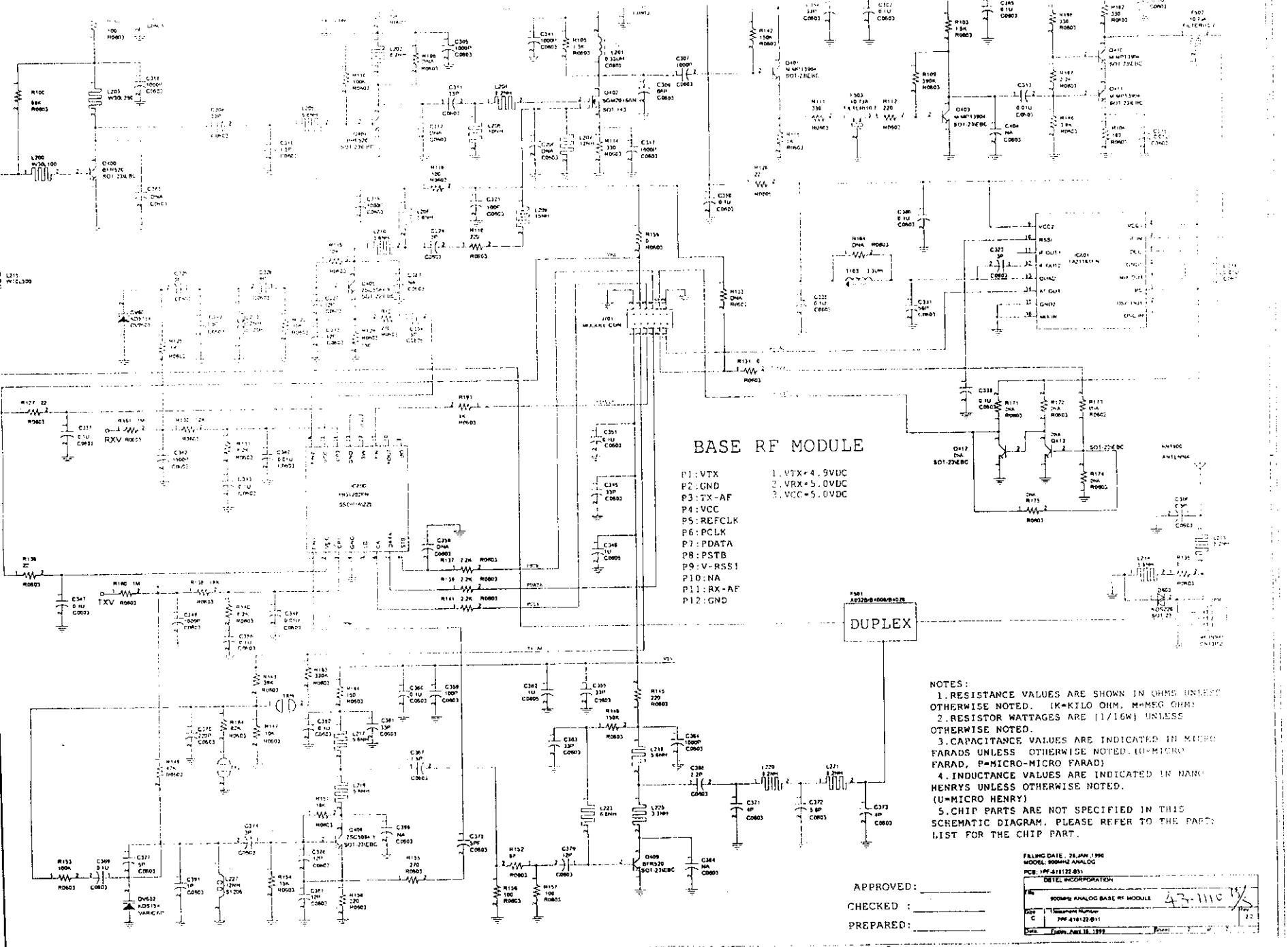

HANDSET RF MODULE
P1:VTX
P2:GND
P3:TX-AF
P4:VCC
P5:REFCLK
P6:PCLK
P7:PDATA
P8:PSTB
P9:V-RSSI
P10:CR-DET
P11:RX-AF
P12:GND
1.VTX=2.9VDC
2.VRX=3.0VDC
3.VCC=3.0VDC
DUPLEX
RXV
TXV
J701 MODULE CON
NOTES:
1.RESISTANCE VALUES ARE SHOWN IN OHMS UNLESS OTHERWISE NOTED. (K=KILO OHM, M=MEG OHM)
2.RESISTOR WATTAGES ARE (1/16W) UNLESS OTHERWISE NOTED.
3.CAPACITANCE VALUES ARE INDICATED IN MICRO FARADS UNLESS OTHERWISE NOTED.(U=MICRO FARAD, P=MICRO-MICRO FARAD)
4.INDUCTANCE VALUES ARE INDICATED IN NANO HENRYS UNLESS OTHERWISE NOTED. (U=MICRO HENRY)
5.CHIP PARTS ARE NOT SPECIFIED IN THIS SCHEMATIC DIAGRAM. PLEASE REFER TO THE PARTS LIST FOR THE CHIP PART.
APPROVED:
CHECKED :
FILLING DATE : 28 JAN. 1999
MODEL: 900MHz ANALOG
DOTEL INCORPORATION
900MHz ANALOG HANDSET RF MODULE
43-1110 H/S



NOTES:
1. RESISTANCE VALUES ARE SHOWN IN OHMS UNLESS OTHERWISE NOTED. (K=KILO OHM, M=MEG OHM)
2. RESISTOR WATTAGES ARE [1/16W] UNLESS OTHERWISE NOTED.
3. CAPACITANCE VALUES ARE INDICATED IN MICRO FARADS UNLESS OTHERWISE NOTED. (U=MICRO FARAD, P=MICRO-MICRO FARAD)
4. INDUCTANCE VALUES ARE INDICATED IN NANO HENRYS UNLESS OTHERWISE NOTED. (U=MICRO HENRY)
5. CHIP PARTS ARE NOT SPECIFIED IN THIS SCHEMATIC DIAGRAM. PLEASE REFER TO THE PARTS LIST FOR THE CHIP PART.

APPROVED: _____
CHECKED : _____
PREPARED: _____

FILING DATE : 26.JAN.1996
MODEL: 900MHz ANALOG
PCB: 7PF-616122-B51

DETEL INCORPORATION

Title	900MHz ANALOG BASE RF MODULE	43-1110
Size	Document Number	Rev
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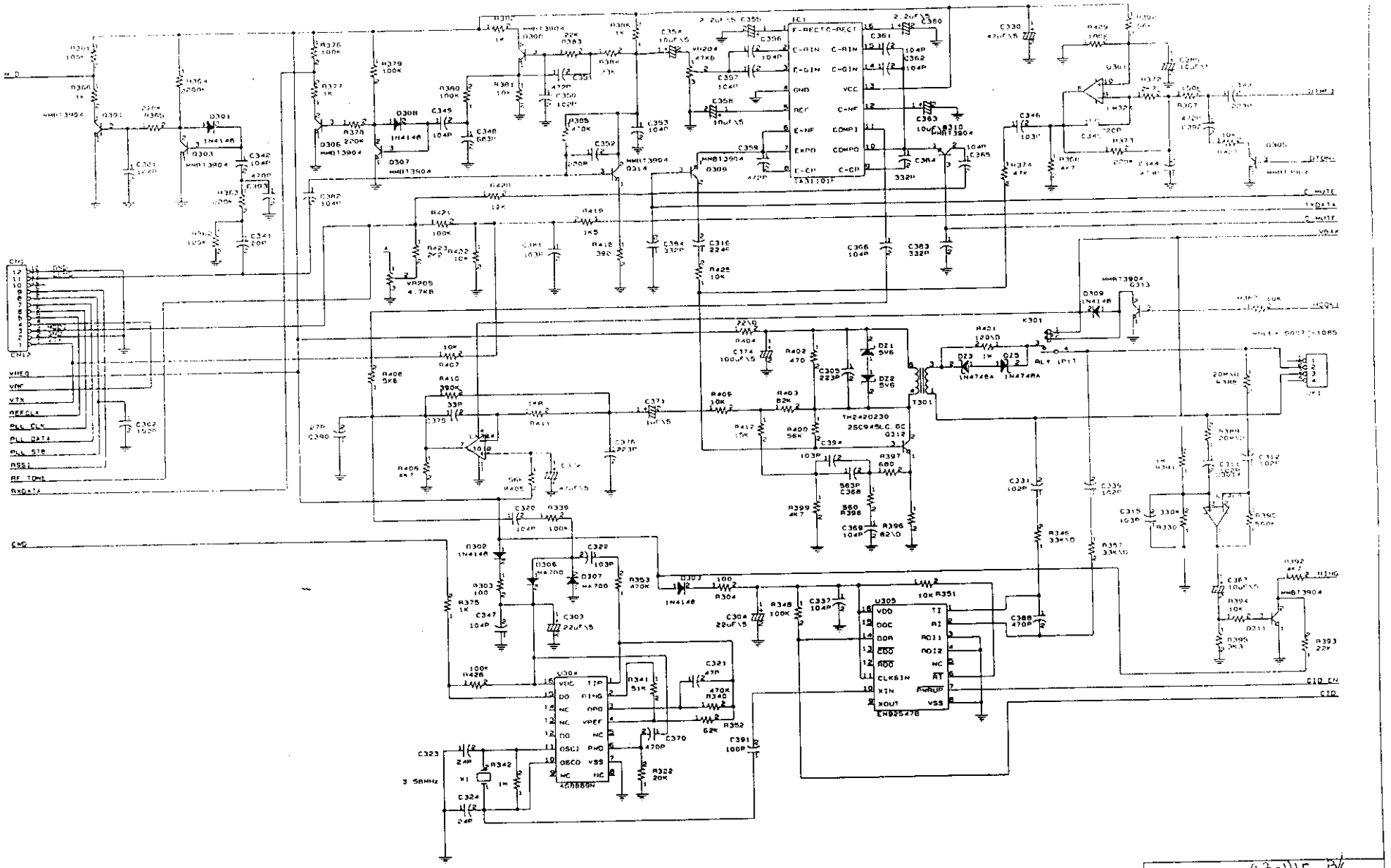
Date	Friday, April 19, 1996	Sheet



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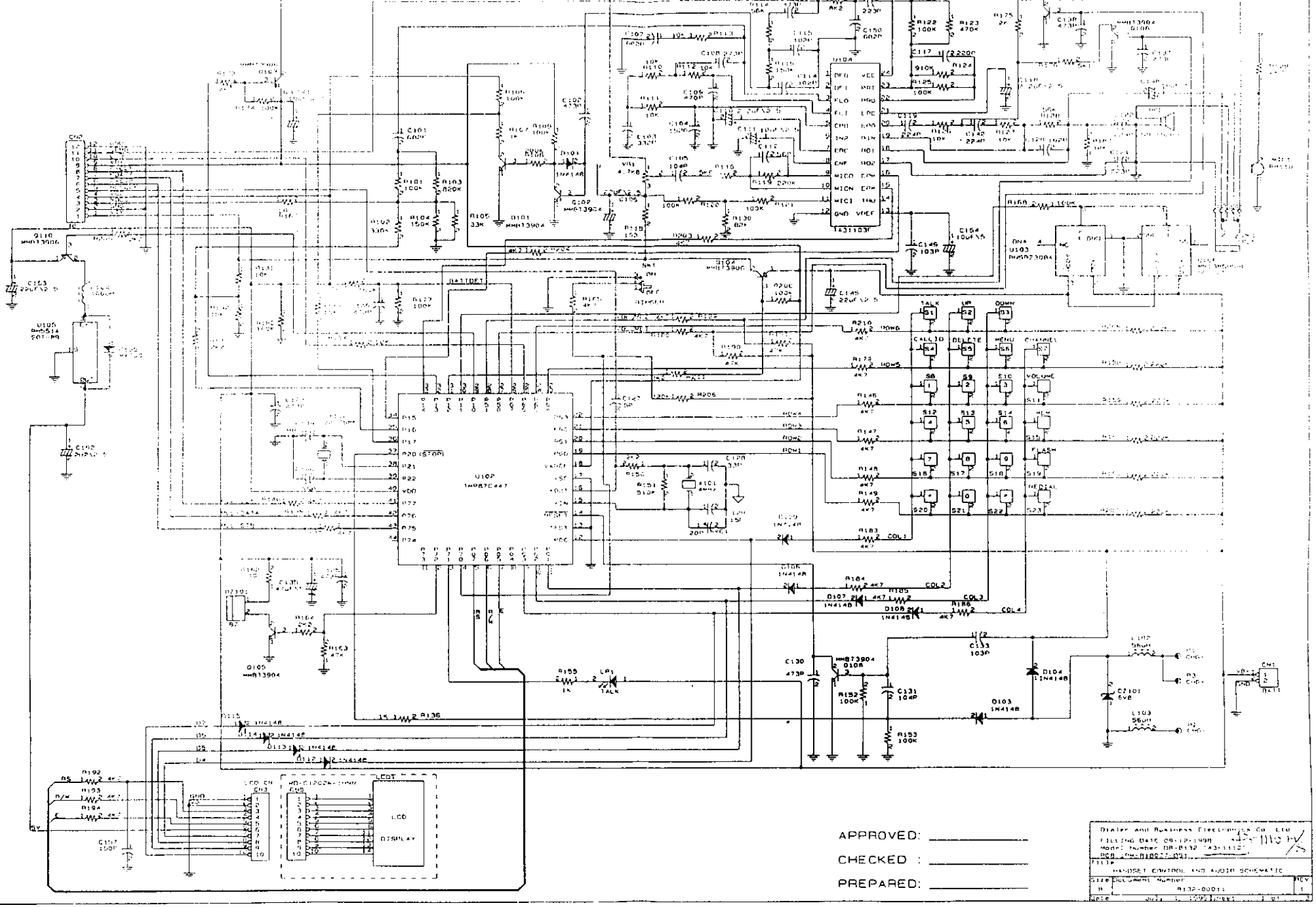
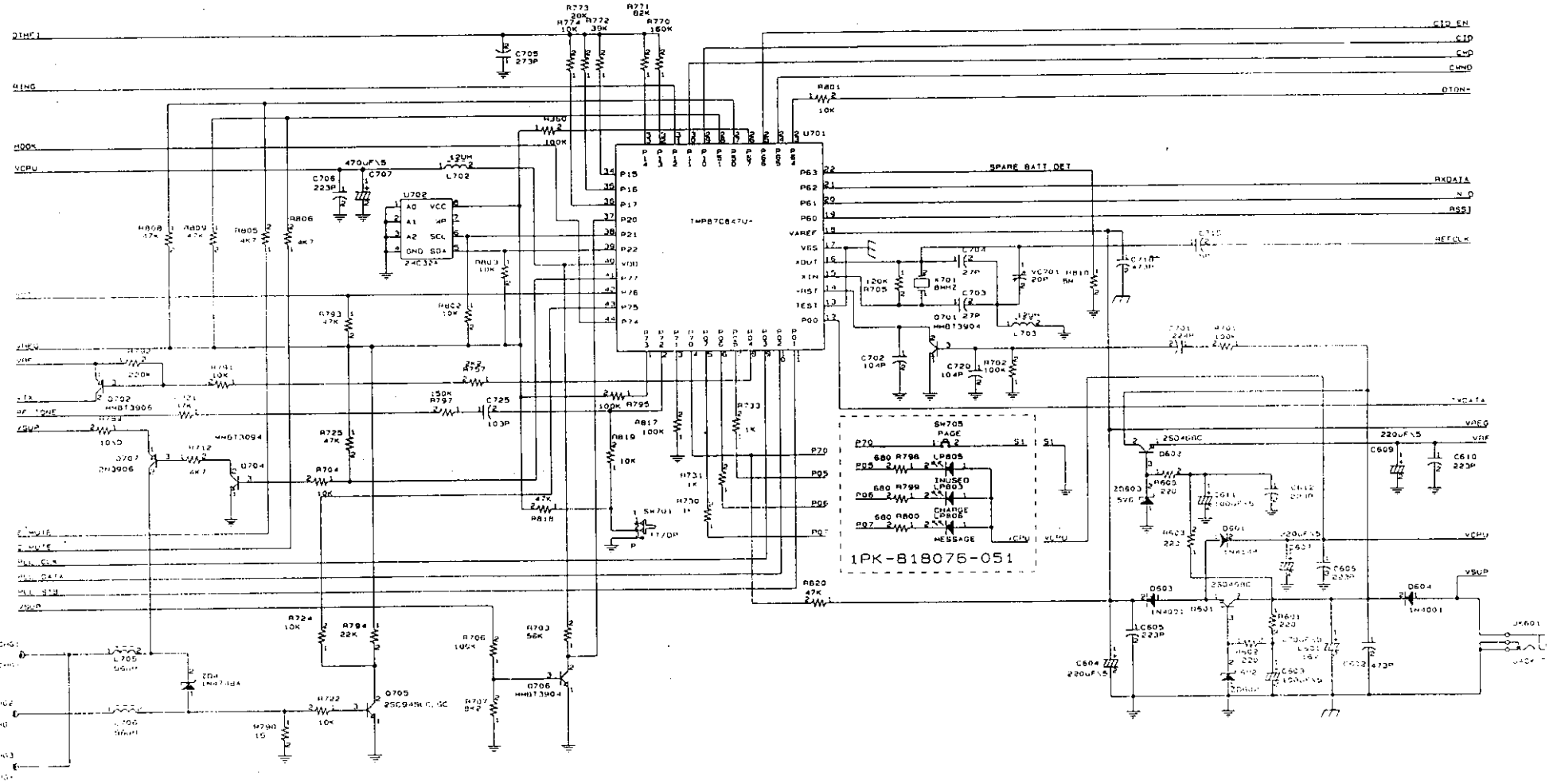
DATE	MARCH 16, 1999 SHEET	OF

43-111E B/S


APPROVED:
CHECKED :
PREPARED:
HANDSET CONTROL AND AUDIO SCHEMATIC



43-1110 B/S

Size	Document Number	REV
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Date:	March 8, 1999 Sheet	of